

L Number	Hits	Search Text	DB	Time stamp
1	0	6572371.uref.	USPAT	2004/06/01 08:21
2	0	6572371.oref.	USPAT	2004/06/01 08:09
3	1	("6109209").PN.	USPAT	2004/06/01 08:10
4	209	118/725.ccls. and reactor.ab. and (deposition oxidation) and "gas"	USPAT	2004/06/01 08:11
5	2	"6572371"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/06/01 08:22
6	1	sion-eric.in.	USPAT	2004/06/01 08:24
7	54	messier-bugatti.as.	USPAT	2004/06/01 08:24
-	245	(432/4).CCLS.	USPAT	2004/06/01 08:08
-	3	(wafer or substrate) and semiconductor and ((432/4).CCLS.)	USPAT	2004/05/28 12:10
-	18	(wafer or substrate) and ((432/4).CCLS.)	USPAT	2004/05/28 12:10
-	0	(wafer or substrate) and semiconductor and ((432/178).CCLS.)	USPAT	2004/05/28 12:12
-	114	(432/178).CCLS.	USPAT	2004/05/28 12:12
-	1	(wafer or substrate) and semiconductor and ((432/207).CCLS.)	USPAT	2004/05/28 12:13
-	232	(432/207).CCLS.	USPAT	2004/05/28 12:13
-	314	(432/247).CCLS.	USPAT	2004/05/28 12:15
-	17	(wafer or substrate) and semiconductor and ((432/247).CCLS.)	USPAT	2004/05/28 12:23
-	297	((432/247).CCLS.) not ((wafer or substrate) and semiconductor and ((432/247).CCLS.))	USPAT	2004/05/28 12:23
-	10	(wafer or substrate) and semiconductor and ((432/245).CCLS.)	USPAT	2004/05/28 12:24
-	122	(432/245).CCLS.	USPAT	2004/05/28 12:27
-	46	(432/93).CCLS.	USPAT	2004/05/28 12:29
-	198	(432/94).CCLS.	USPAT	2004/05/28 12:34
-	0	("reactor.ab.and(wafer substrate)andsemiconductorand"gasinlet"and	USPAT	2004/05/28 12:35
-	115	reactor.ab. and (wafer substrate) and semiconductor and "gas inlet" and "gas outlet" and heat\$4	USPAT	2004/05/28 12:57
-	20150	reactor.bsum. and (deposition oxidation) and "gas" and temperature and heat\$4	USPAT	2004/05/28 12:59
-	4721	reactor.ab. and (deposition oxidation) and "gas" and temperature and heat\$4	USPAT	2004/05/28 12:59
-	1059	reactor.ti. and (deposition oxidation) and "gas" and temperature and heat\$4	USPAT	2004/05/28 12:59
-	419	(wafer substrate) and (reactor.ti. and (deposition oxidation) and "gas" and temperature and heat\$4)	USPAT	2004/05/28 13:00
-	379	((wafer substrate) and (reactor.ti. and (deposition oxidation) and "gas" and temperature and heat\$4)) not (reactor.ab. and (wafer substrate) and semiconductor and "gas inlet" and "gas outlet" and heat\$4)	USPAT	2004/05/28 13:54
-	15	susceptor.ab. and 432/\$.ccls. and (wafer substrate)	USPAT	2004/05/28 13:57
-	174	susceptor.ab. and 219/\$.ccls. and (wafer substrate)	USPAT	2004/05/28 13:57

-	170	(susceptor.ab. and 219/\$.ccls. and (wafer substrate)) not (susceptor.ab. and 432/\$.ccls. and (wafer substrate))	USPAT	2004/05/28 14:23
-	1000	((219/390) or (219/405)).CCLS.	USPAT	2004/05/28 14:23
-	312	(wafer substrate) and (deposition oxidation) and (((219/390) or (219/405)).CCLS.)	USPAT	2004/05/28 14:28
-	279	((wafer substrate) and (deposition oxidation) and (((219/390) or (219/405)).CCLS.)) not (((susceptor.ab. and 219/\$.ccls. and (wafer substrate)) not (susceptor.ab. and 432/\$.ccls. and (wafer substrate))) (susceptor.ab. and 432/\$.ccls. and (wafer substrate)) ((wafer substrate) and (reactor.ti. and (deposition oxidation) and "gas" and temperature and heat\$4)) not (reactor.ab. and (wafer substrate) and semiconductor and "gas inlet" and "gas outlet" and heat\$4)))	USPAT	2004/05/28 14:49
-	800	((392/416) or (392/418)).CCLS.	USPAT	2004/05/28 14:50
-	243	(wafer substrate) and "gas" and (reactor vessel susceptor furnace oven) and (((392/416) or (392/418)).CCLS.)	USPAT	2004/05/28 14:51
-	138	((wafer substrate) and "gas" and (reactor vessel susceptor furnace oven) and (((392/416) or (392/418)).CCLS.)) not (((wafer substrate) and (deposition oxidation) and (((219/390) or (219/405)).CCLS.)) not (((susceptor.ab. and 219/\$.ccls. and (wafer substrate)) not (susceptor.ab. and 432/\$.ccls. and (wafer substrate))) (susceptor.ab. and 432/\$.ccls. and (wafer substrate)) ((wafer substrate) and (reactor.ti. and (deposition oxidation) and "gas" and temperature and heat\$4)) not (reactor.ab. and (wafer substrate) and semiconductor and "gas inlet" and "gas outlet" and heat\$4))))	USPAT	2004/05/28 14:51
-	1	("4693777").PN.	USPAT	2004/05/28 15:17
-	1	("6495805").PN.	USPAT	2004/05/28 15:38